

pSEMI MATERIAL DECLARATION FORM

Product:	PE43670
Ordering Codes:	PE43670A-Z
Description:	UltraCMOS® 50 Ω RF Digital Attenuator 7-bit, 31.75 dB, 9 kHz-4.0 GHz
Package:	32L 5x5 QFN
Environmental Compliance	EU RoHS Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	2.020438	3.13%	31,290.98
Die	Aluminum	7429-90-5	0.006146	0.01%	95.18
Die	Silicon	7440-21-3	0.000410	0.00%	6.35
Die	Arsenic	7440-38-2	0.000002	0.00%	0.03
Die	Boron	7440-42-8	0.000002	0.00%	0.03
Die	Phosphorus	7723-14-0	0.000008	0.00%	0.13
Die	Titanium	7440-32-6	0.001024	0.00%	15.86
Die	Tungsten	7440-33-7	0.020486	0.03%	317.27
Die	Cobalt	7440-48-4	0.000041	0.00%	0.63
Die	Copper	7440-50-8	0.000016	0.00%	0.25
Leadframe	Copper	7440-50-8	26.714000	41.37%	413,725.62
Leadframe	Iron	7439-89-6	0.643900	1.00%	9,972.22
Leadframe	Zinc	7440-66-6	0.032900	0.05%	509.53
Leadframe	Phosphorous	7723-14-0	0.008200	0.01%	127.00
Die Attach	Silver	7440-22-4	0.287200	0.44%	4,447.93
Die Attach	Epoxy Resin	9003-36-5	0.035900	0.06%	555.99
Die Attach	Diluent	26447-14-3	0.021500	0.03%	332.98
Die Attach	Dicyandiamide	461-58-5	0.003600	0.01%	55.75
Die Attach	Hardener	620-92-8	0.010800	0.02%	167.26
Wire	Gold	7440-57-5	0.552900	0.86%	8,562.88
Plating	Others	Proprietary	0.000100	0.00%	1.55
Plating	Nickel	7440-02-0	0.180330	0.28%	2,792.81
Plating	Palladium	7440-05-3	0.014580	0.02%	225.80
Plating	Gold	7440-57-5	0.000580	0.00%	8.98
Molding Compound	Silica Fused	60676-86-0	31.191100	48.31%	483,063.46
Molding Compound	Epoxy Resin	Trade secret	1.360600	2.11%	21,071.91
Molding Compound	Phenol Resin	Trade secret	1.360600	2.11%	21,071.91
Molding Compound	Carbon Black	1333-86-4	0.102000	0.16%	1,579.70
Total Weight (mg)			64.569364	100.00%	1,000,000